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(12) **United States Design Patent** (10) **Patent No.:** **US D836,616 S**
Escaro (45) **Date of Patent:** **** Dec. 25, 2018**

- (54) **RFID INLAY**
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- (**) Term: **15 Years**
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- (22) Filed: **Jun. 15, 2017**

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Related U.S. Application Data

- (62) Division of application No. 29/573,567, filed on Aug. 8, 2016, now Pat. No. Des. 794,001.

Foreign Application Priority Data

- Feb. 18, 2016 (JP) 2016-003538
- Feb. 18, 2016 (JP) 2016-003539

- (51) **LOC (11) Cl.** **14-03**
- (52) **U.S. Cl.**
USPC **D14/230**

- (58) **Field of Classification Search**
USPC D14/230, 138, 135, 231-238, 238.1, 299, D14/358; D12/42, 43
CPC G01R 29/10; G01S 2013/0245; G01S 2013/0254; G01S 2013/0263; G01S 7/4026
See application file for complete search history.

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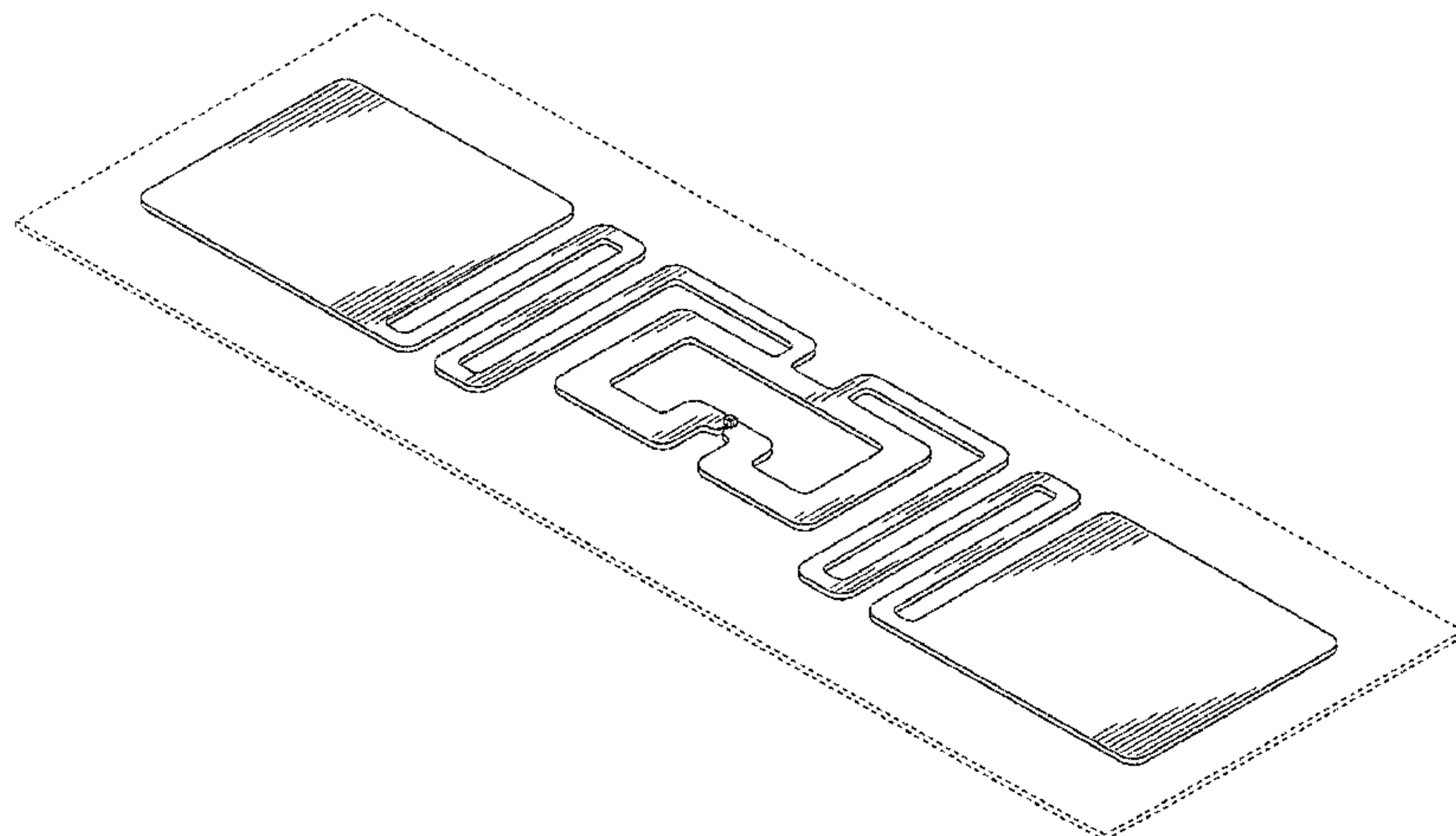
(57) **CLAIM**

The ornamental design for an RFID inlay, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of a RFID inlay.
 FIG. 2 is a front view of FIG. 1.
 FIG. 3 is a top elevation view of FIG. 1.
 FIG. 4 is a bottom plan view of FIG. 1.
 FIG. 5 is a right side view of FIG. 1.
 FIG. 6 is a left side view of FIG. 1; and,
 FIG. 7 is an illustrative sectional view along section 7-7 in FIG. 2.
 The broken lines represent portions of the RFID inlay that form no part of the claimed design.

1 Claim, 4 Drawing Sheets



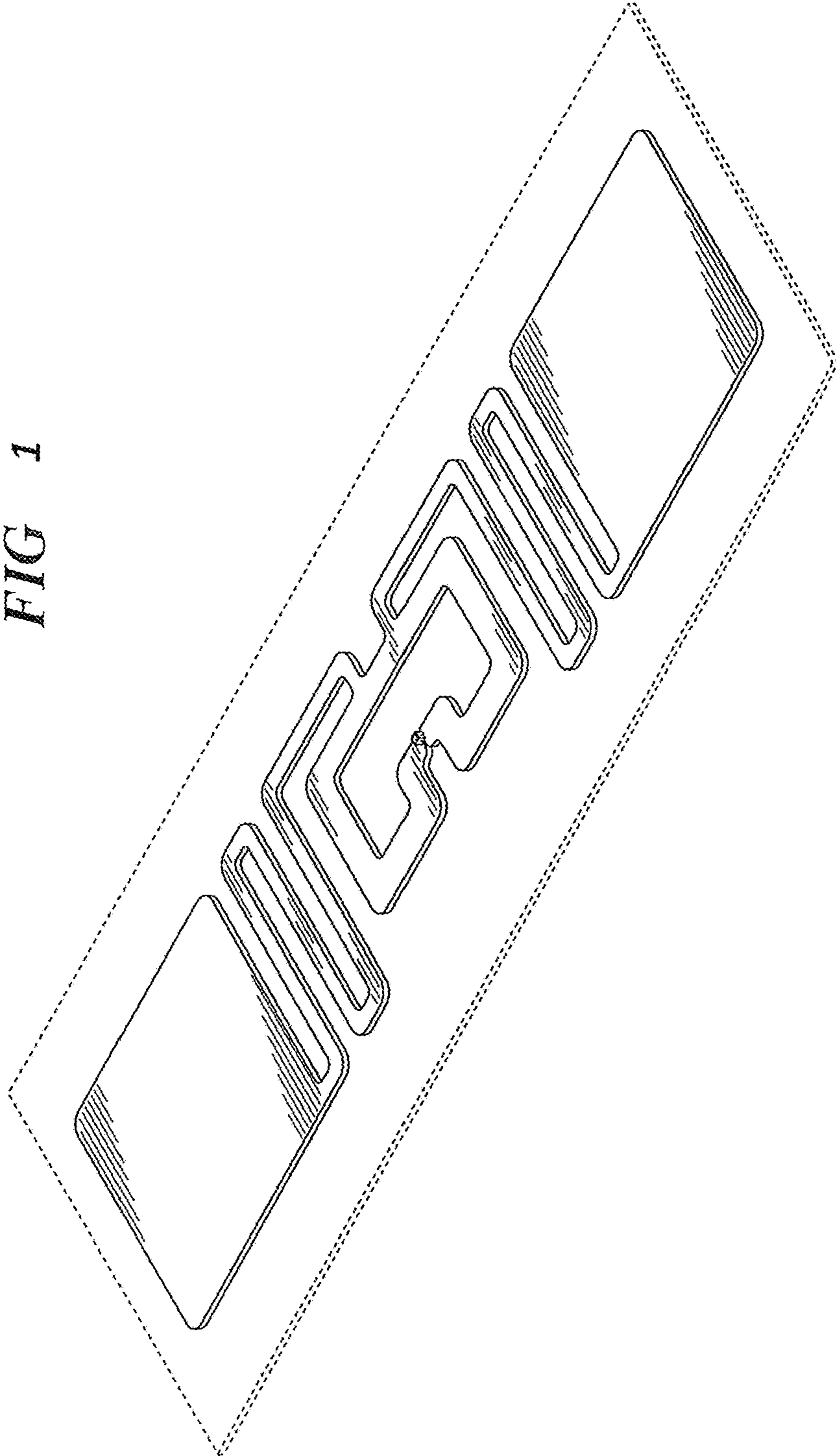


FIG 1

FIG. 2

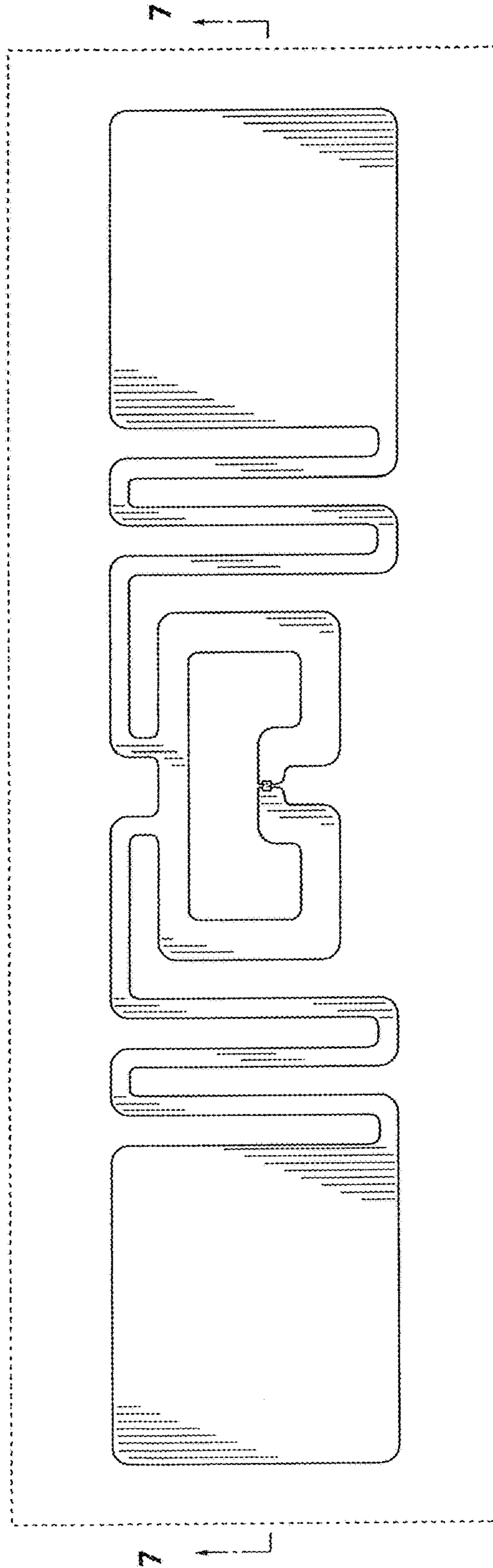


FIG. 3

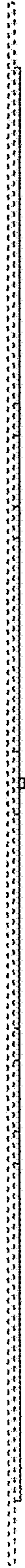


FIG. 4

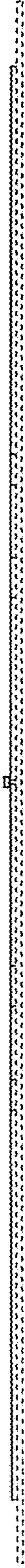


FIG. 7



FIG. 5

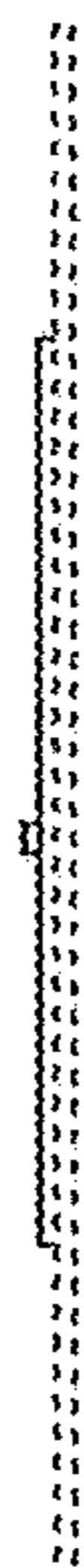


FIG. 6

